

Product Advisory

Issue Date: 03-June-2021

Change Description:

Addition of dry film solder resist in substrate manufacturing

Parts Affected:

BCM47622A1FEBG

BCM476221KFEBG

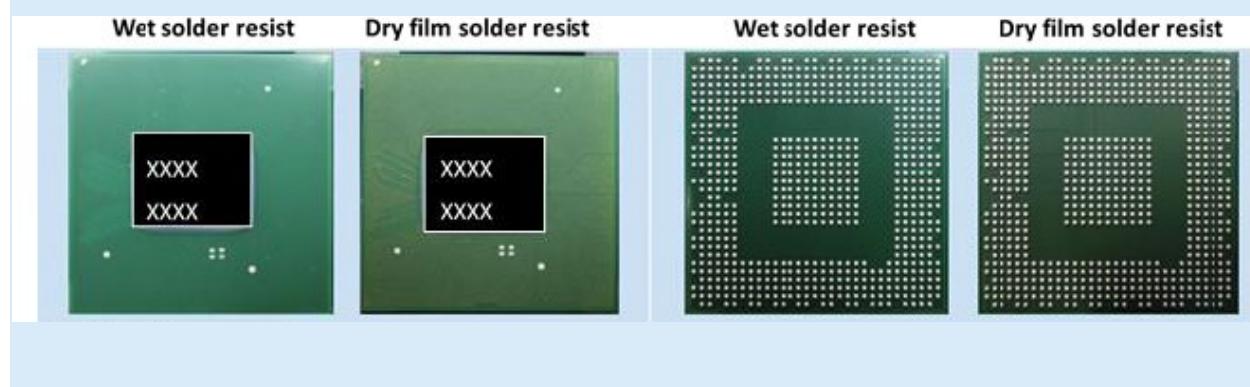
BCM47622LA1KFEBG

BCM6755A1KFEBG

Description and Extent of Change:

Addition of dry film solder resist to current wet solder resist process. Dry solder resist film is translucent, and is currently used in production on other Broadcom high volume products. Dry solder resist film is Form, Fit and Function identical to the wet solder resist currently used, except for the cosmetic difference. Use of the dry solder resist film has no impact to customers SMT process.

Images below from another device is an example of the cosmetic difference:



Reasons for Change:

Manufacturing flexibility to add more capacity and increase throughput.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

The device specification will remain the same, which will ensure product electrical performance remains the same. Appropriate electrical characterization and reliability qualification has been performed on representative products to ensure normal parametric distribution, consistent electrical performance, and reliability.

Effective Date of Change:

Product shipments using this change will begin shipping interchangeably after 15-July-2021. Timing of shipments for these parts will vary by part number depending on customer demand, and inventory levels.

Qualification Data:

Qualification Data has been generated and approved. Please reference the table below.

Stress Test	Condition	Read points	Sample Size	Requirements	Results
		Cycles / Hrs.			
Precondition	MSL3 JESD22-A113E		170 units	0 failures	0 / 170
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	85 units	0 failures	0 / 85
uHast	130°C/85%RH JEDEC Std. 22-A102-C	96hrs	85 units	0 failures	0 / 85
HTSL	TA=150°C	1000hrs	85 units	0 failures	0 / 85

